

Pin Assignment

The TSL257 pin assignments are described below.

Figure 3:
Pin Diagram of Package S Sidelooker (Front View)

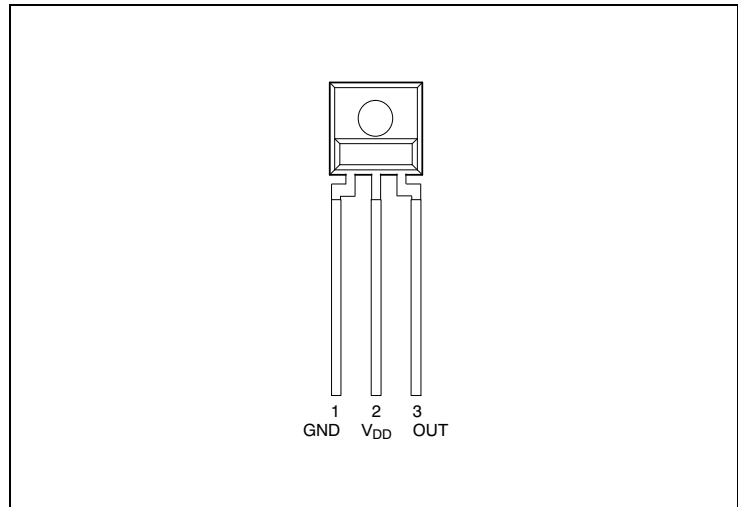


Figure 4:
Pin Diagram of Package SM Surface Mount Sidelooker (Front View)

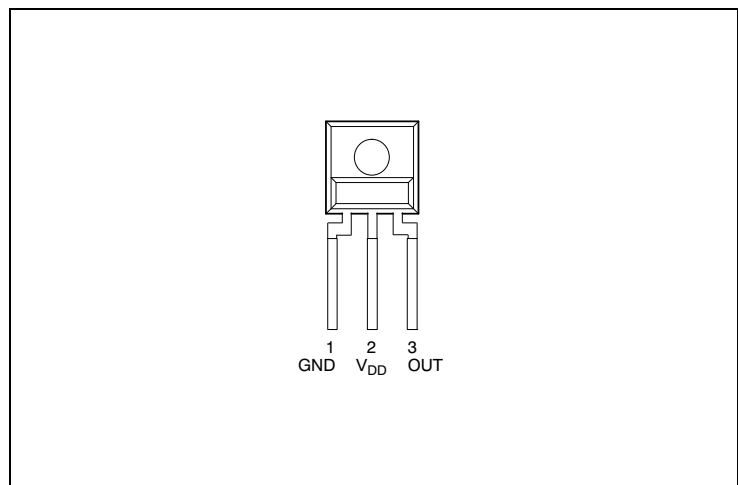


Figure 5:
Terminal Functions

Terminal		Description
No.	Name	
1	GND	Ground (substrate). All voltages are referenced to GND.
2	V _{DD}	Supply voltage
3	OUT	Output voltage

Absolute Maximum Ratings

Stresses beyond those listed under [Absolute Maximum Ratings](#) may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under [Operating Conditions](#) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 6:
Absolute Maximum Ratings over Operating Free-Air Temperature Range (unless otherwise noted)

Symbol	Parameter	Min	Max	Unit
V_{DD}	Supply voltage ⁽¹⁾		6	V
I_O	Output current		±10	mA
	Duration of short-circuit current at (or below) 25°C		5	s
T_A	Operating free-air temperature range	-25	85	°C
T_{STRG}	Storage temperature range	-25	85	°C
	Lead temperature 1.6mm (1/16 inch) from case for 10 seconds (S Package)		260	°C
	Reflow solder, in accordance with J-STD-020C or J-STD-020D (SM Package)		260	°C

Note(s):

1. All voltages are with respect to GND.